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Change List

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2	Block Diagram					
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4	Sch					
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LAST_MODIFICATION:

LAST_MODIFICATION:

	QTY	DESCRIPTION
SCH		
PCB		
BOM		


	Project	my_heat.PrjPcb
	Title	01_Table of Contents.SchDoc
Drawn by		*
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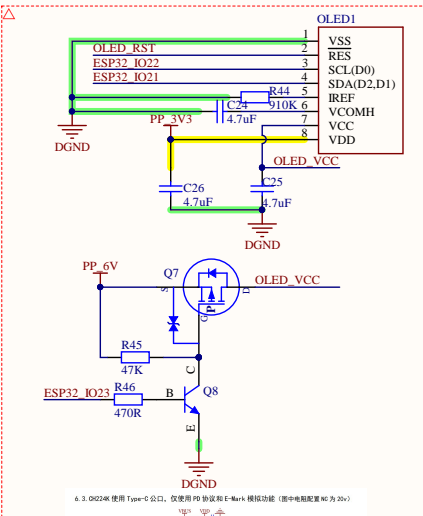
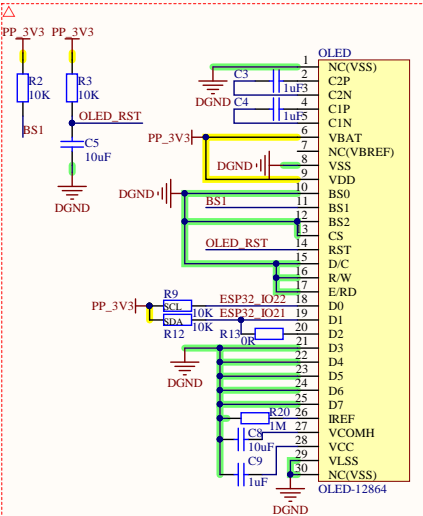
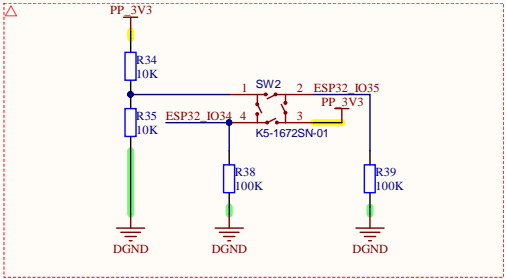
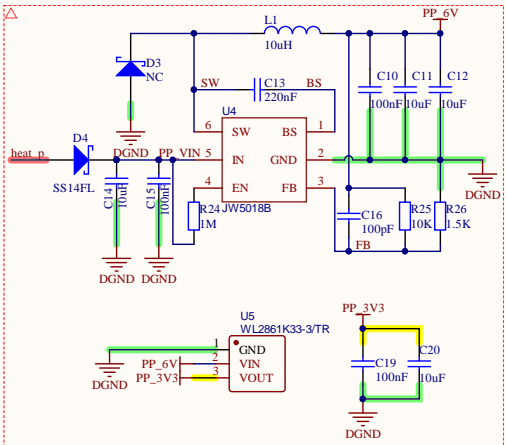
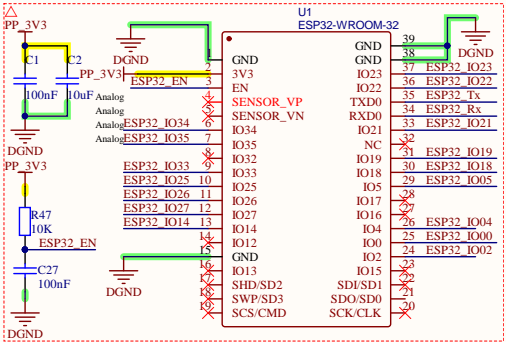
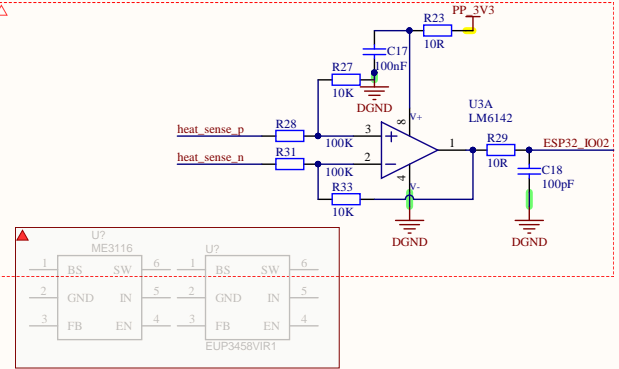
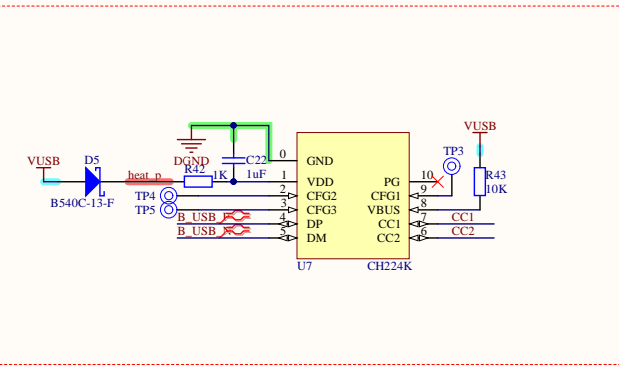
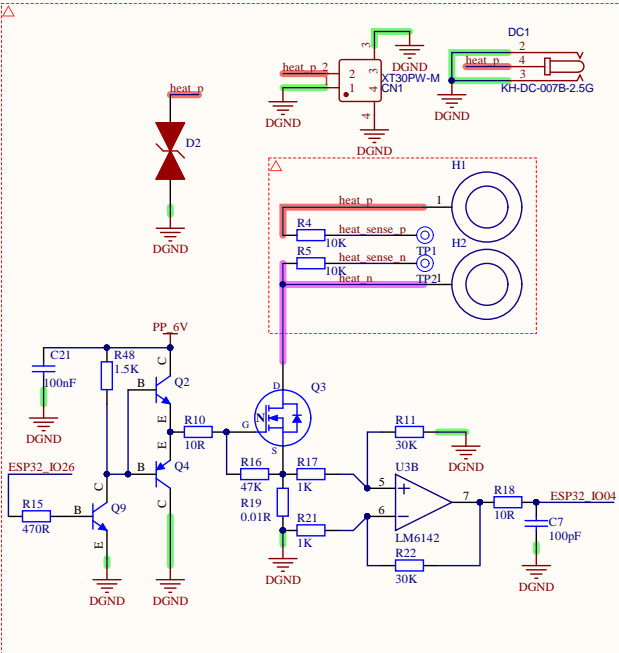
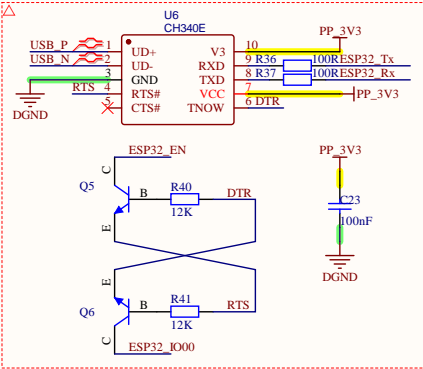
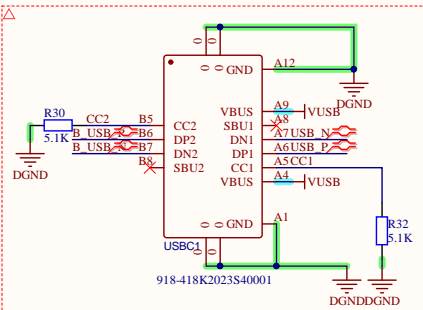
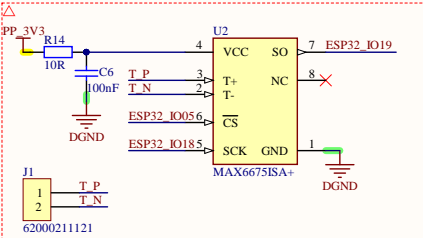
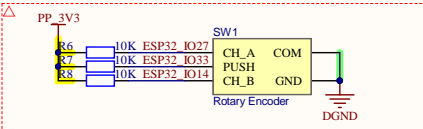
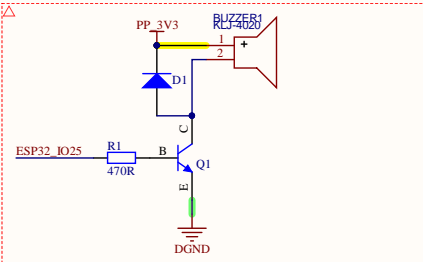
	1	2	3	4	5	6	7	8
A	Page2:Block Diagram							
B								
C								
D								
	1	2	3	4	5	6	7	8

	Project	my_heat.PrjPcb
	Title	02_Block Diagram.SchDoc
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Date	*	

	1	2	3	4	5	6	7	8
A								
B								
C								
D								
	1	2	3	4	5	6	7	8

Page3:Power Tree


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Date		*

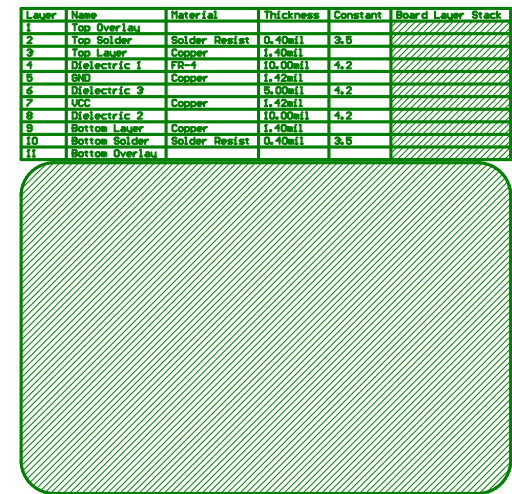


25 R_25 = 2.82 Ohm
= 0.0175 Ohm*mm^2/m @20°C
TCR 0.003951/°C
2.82R @25°C
2.82R*(1 + TCR*(285-25)°C) = 5.71R @285
2.0Text

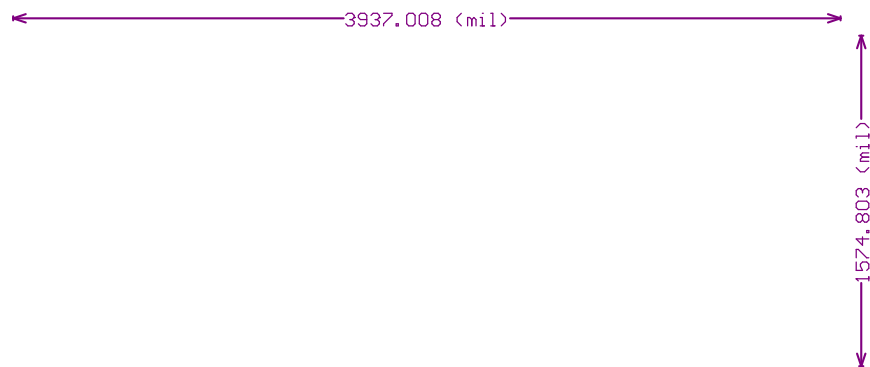
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Title	04_Sch.SchDoc
Drawn by	*
Version	*
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Date	*

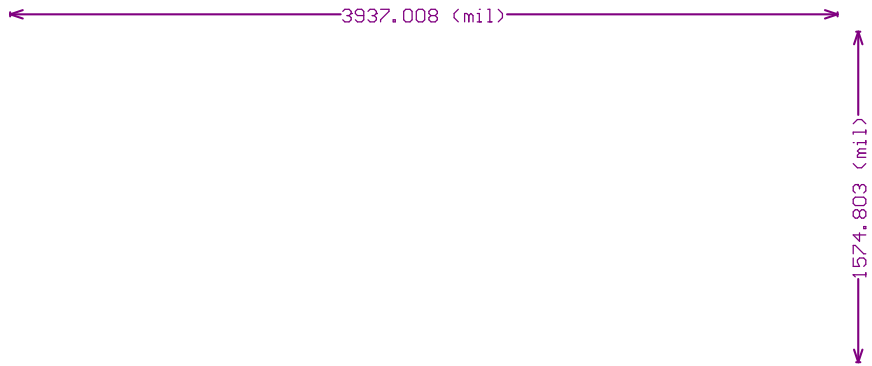
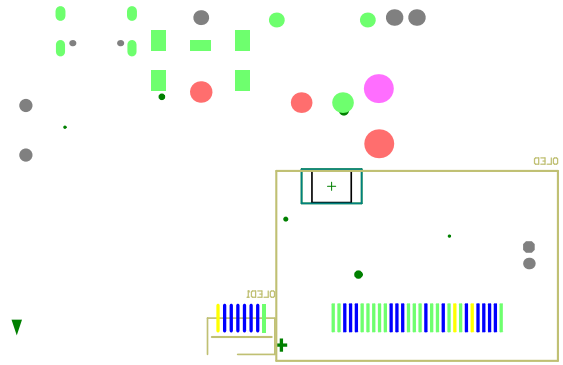
	1	2	3	4	5	6	7	8
A								
B								
C								
D								
	1	2	3	4	5	6	7	8

	Project	my_heat.PrjPcb
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Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mi	3.5	
3	Top Layer	Copper	1.40mi		
4	Dielectric 1	FR-4	10.00mi	4.2	
5	Prep		1.42mi		
6	Dielectric 3	Copper	1.40mi	4.2	
7	UCC	Copper	1.42mi		
8	Dielectric 2		10.00mi	4.2	
9	Bottom Layer	Copper	1.40mi		
10	Bottom Solder	Solder Resist	0.40mi	3.5	
11	Bottom Overlay				





[illegible]